

Infonote

AO-IN-2023-024-I

Introduction of 3rd Optical Visual Inspection for Die Attach Process for SMT Lidar

15.06.2023

Dear Customer,

please take note of this **Infonote**.

This customer notification is for information only and does not require customer approval.

Objective:	Introduction of 3rd Optical Visual Inspection for Die Attach Process for SMT Lidar
Affected products:	Refer to document 2_cip_AO-IN-2023-024-I
Reason for change:	With additional 3rd optical visual inspection for die attach (DA) process will improve inspection at die surface.
Description of change:	For details refer to file 2_cip_AO-IN-2023-024-I
Time schedule:	Intended start of introduction: July 4 th , 2023 (CW28)
Assessment:	○ No change in the physical dimensions ○ No changes in electrical parameters ○ No changes in reliability
Documentation:	Customer information package 2_cip_AO-IN-2023-024-I

Material (Q-no.)	MQD	Device Family	Status
Q65112A6166	SPL S1L90A_3 A01	SPL S1L90A_3 A01	10
Q65112A6167	SPL S4L90A_3 A01	SPL S4L90A_3 A01	10
Q65112A8856	SPL S1L90A_3 A01 C1025	SPL S1L90A_3 A01	10
Q65113A4598	SPL S1L90H_3	SPL S1L90H_3	3
Q65113A5607	SPL S4L90A_3 A01 C1004	SPL S4L90A_3 A01	10
Q65113A5832	SPL S8L91A_3 A01	SPL S4L90A_3 A01	3
Q65113A5924	SPL S1L90A_3 A01 C1036	SPL S1L90A_3 A01	10